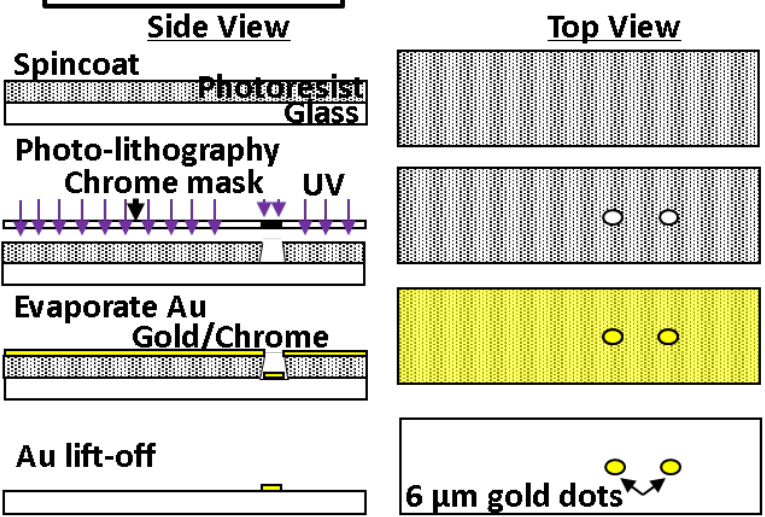
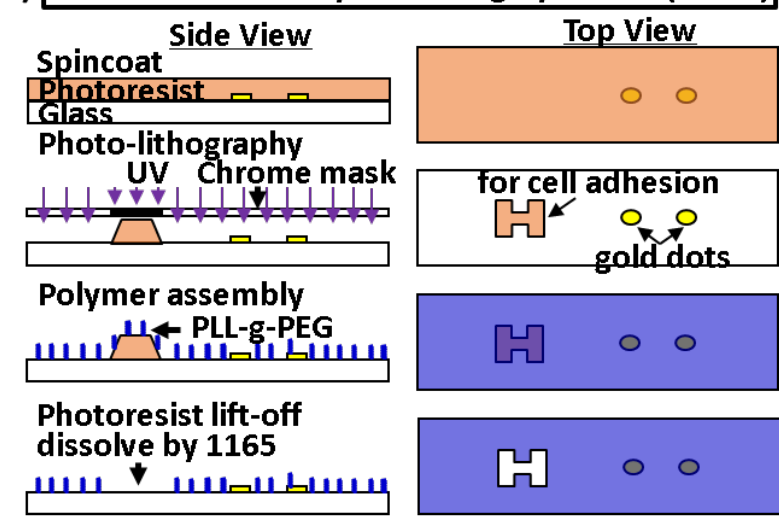


a) Gold Deposition



b) Molecular-Assembly Patterning by Lift-off (MAPL)



c) Chip Assembly

